Data Sheet

Photocoupler
LTV-2630 series

1. DESCRIPTION

The LTV-2630 consists of a high efficient AlGaAs Light Emitting Diode and a high speed optical detector. This design provides excellent AC and DC isolation between the input and output sides of the Optocoupler. The output of the optical detector features an open collector Schottky clamped transistor. A guaranteed common mode transient immunity is up to 10kV/μs at 3.3V.The Optocoupler operational parameters are guaranteed over the temperature range from -40ºC ~ +110ºC.

1.1 Features

- 3.3V / 5V Dual Supply Voltages
- Low power consumption
- High speed – 10MBd typical
- 10kV/μs minimum Common Mode Rejection (CMR) at V_{CM} = 1000V
- Guaranteed AC and DC performance over temperature -40ºC ~ +110ºC.
- LVTTL/LVCMOS Compatible.
- Available in Dual-in-line, Wide lead spacing, Surface mounting package.
- Safety approval

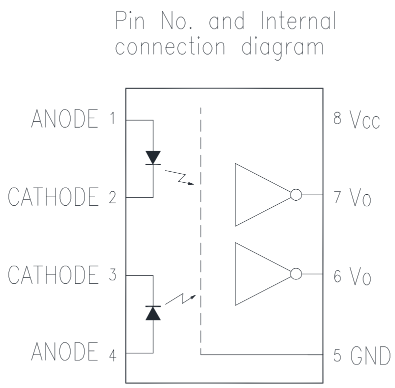
  UL/ cUL 1577, 5000 Vrms/1 min

  VDE DIN EN60747-5-5, V_{IORM} = 567 Vpeak

1.2 Applications

- Isolation in line receivers
- Digital isolation for A/D, D/A conversion
- Ground loop elimination
- Feedback Element in Switching Mode Power Supplier
- Pulse transformer replacement
- Power transistor isolation in motor drives
- Interface between Microprocessor system, computer and their peripheral

1.3 Functional Diagram



Truth Table (Positive Logic)

LED	OUT
ON	L
OFF	H

A 0.1μF bypass Capacitor must be connected between Pin8 and Pin5

2. TYPE

Part number	Lead Frame		Suffix option			Quantity
	Type	Clearance distance	Tape & Reel	Pin 1 location	IEC/EN/DIN EN60747-5-5	
LTV-2630	Through hole	Typ. 7 mm			-V*	1000 per reel 65 per tube
LTV-2630M	Wide lead	Typ. 8 mm				
LTV-2630S	Surface mount	Typ. 8 mm	-TA	lower right of the tape		
LTV-2630S2	Surface mount 2	Min. 8 mm	-TA1	upper left of the tape		

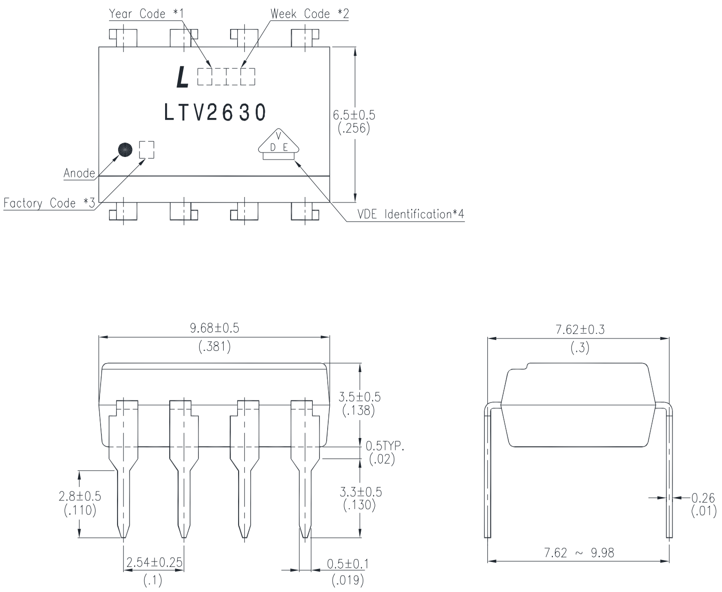
Example 1 : LTV-2630S-TA1

Example 2 : LTV2630STA1-V

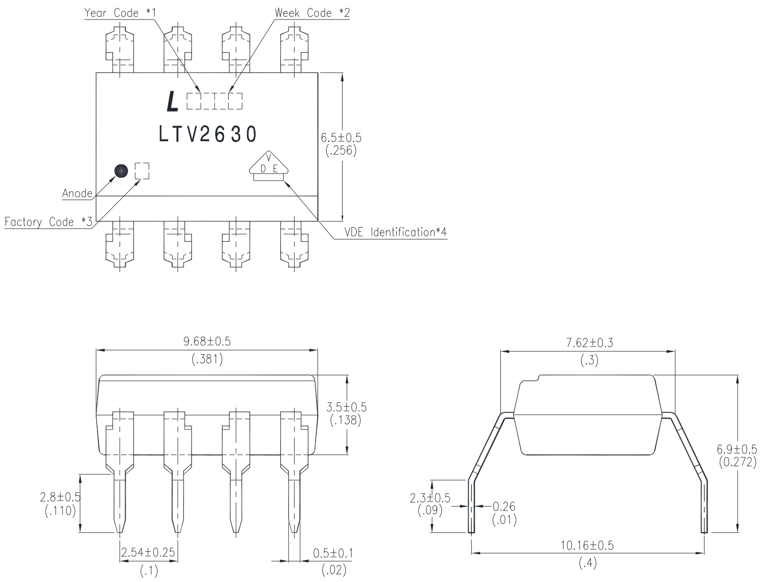
* Naming rule of VDE option : All ”-” before -V be removed.

3. PACKAGE DIMENSIONS

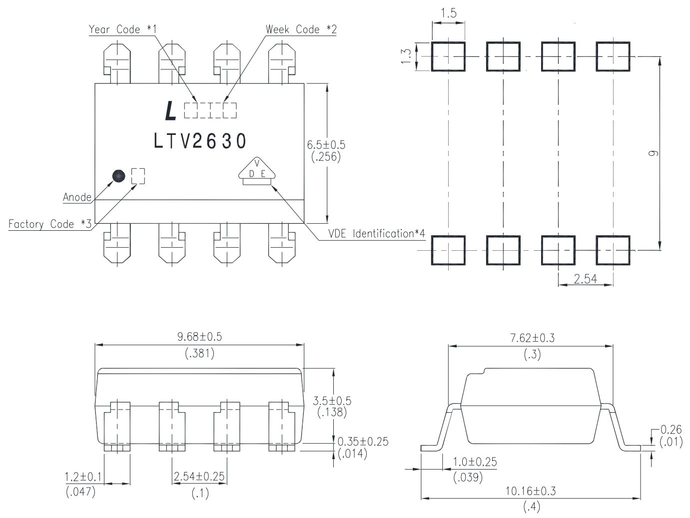
3.1 LTV-2630



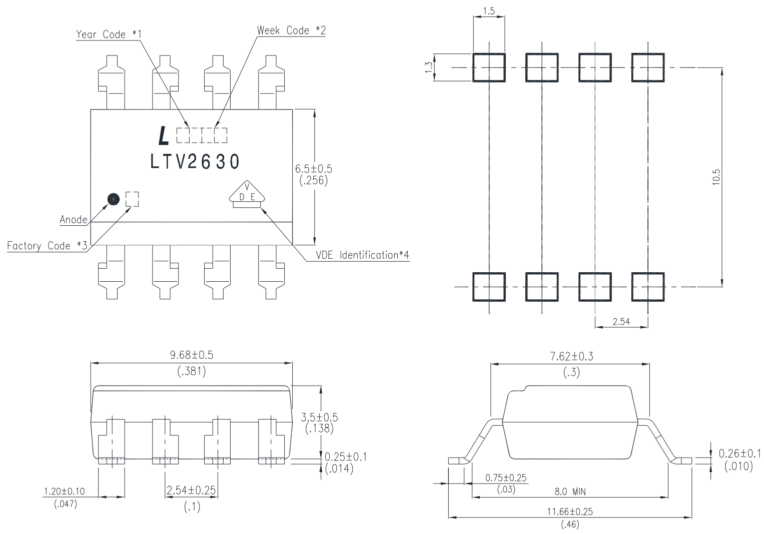
3.2 LTV-2630M



3.3 LTV-2630S



3.4 LTV-2630S2



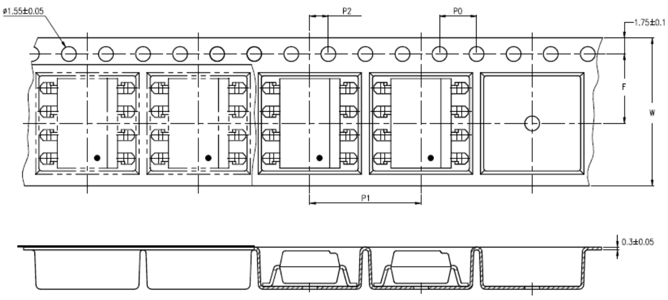
Notes :

1. 2-digit year code, example : 2017 = 17
2. 2-digit work week ranging from '01' to '52'
3. Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
4. VDE identification mark (option).

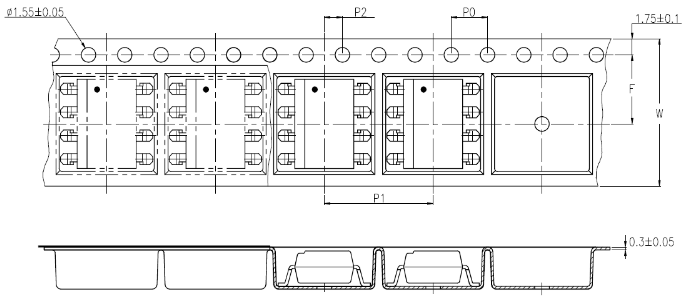
Dimensions in millimeters (inches).

4. TAPING DIMENSIONS

4.1 LTV-2630S-TA

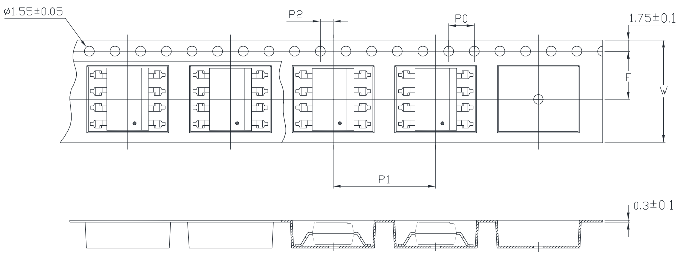


4.2 LTV-2630S-TA1

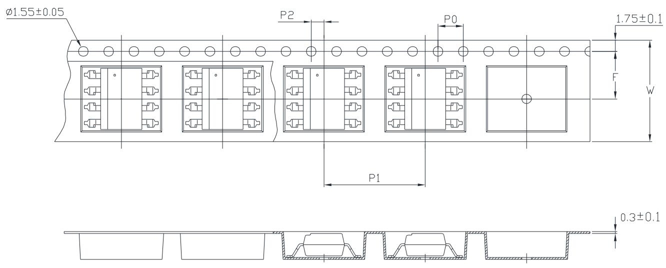


Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P_0	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
	P_2	2±0.1 (0.079)
Distance of compartment to compartment	P_1	12±0.1 (0.472)

4.3 : LTV-2630S2-TA



4.4 : LTV-2630S2-TA1



Description	Symbol	Dimension in mm (inch)
Tape wide	W	16±0.3 (0.63)
Pitch of sprocket holes	P_0	4±0.1 (0.15)
Distance of compartment	F	7.5±0.1 (0.295)
	P_2	2±0.1 (0.079)
Distance of compartment to compartment	P_1	12±0.1 (0.472)

5. RATING AND CHARACTERISTICS

5.1 Absolute Maximum Ratings at Ta=25°C

	Parameter	Symbol	Rating	Unit	Note
Input	Average Forward Input Current	I_F	20	mA	2
	Reverse Input Voltage	V_R	5	V	
	Power Dissipation	P_I	40	mW	
Output	Output Collector Current	I_O	50	mA	
	Output Collector Voltage	V_O	7	V	
	Output Collector Power Dissipation	P_o	85	mW	
	Isolation Voltage	V_{iso}	5000	V_{rms}	
	Supply Voltage	V_{CC}	7	V	
	Operating Temperature	T_{opr}	-40 ~ +110	°C	
	Storage Temperature	T_{stg}	-55 ~ +125	°C	
	Lead Solder Temperature *2	T_{sol}	260	°C	

1. Ambient temperature = 25°C, unless otherwise specified. Stresses exceeding the absolute maximum ratings can cause permanent damage to the device. Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

2. 260°C for 10 seconds. Refer to Lead Free Reflow Profile.

5.2 Recommended Operating Conditions

Parameter	Symbol	Min.	Max.	Unit
Operating Temperature	T_A	-40	110	°C
Supply Voltage	V_{CC}	2.7	3.6	V
		4.5	5.5	
Low Level Input Current	I_{FL}	0	250	μA
High Level Input Current	I_{FH}	5	15	mA
Output Pull-up Resistor	R_L	330	4k	Ω
Fan Out (at R_L=1kΩ per channel)	N	—	5	TTL Loads

5.3 ELECTRICAL OPTICAL CHARACTERISTIC

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition	Fig.	Note
Input								
Input Forward Voltage	V_F	—	1.38	1.80	V	I_F=10mA, T_A=25°C	5	
Input Forward Voltage Temperature Coefficient	$\Delta V_F/\Delta T$	—	-1.5	—	mV/°C	I_F=10mA		
Input Reverse Voltage	BV_R	5.0	—	—	V	I_R = 10μA		
Input Threshold Current	I_{TH}	—	2	5	mA	V_{CC} = 3.3V, V_O = 0.6V I_{OL} (sinking) = 13mA	6	
Input Capacitance	C_{IN}	—	34	—	pF	V_F=0; f=1MHz		
Detector								
Logic low output voltage	V_{OL}	—	0.24	0.6	V	V_{CC} = 3.3V, I_F = 5mA, I_{OL} (sinking) = 13mA	8	
Logic high output current	I_{OH}	—	1.3	100	μA	V_{CC} = 3.3V, V_O = 3.3V, I_F = 250μA	4	
Logic low supply current	I_{CCL}	—	6.4	10	mA	V_{CC} = 3.3V, I_F = 10mA		1
Logic high supply current	I_{CCH}	—	6.8	10	mA	V_{CC} = 3.3V, I_F = 0mA		1

Specified over recommended temperature (T_A = -40°C to +110°C, 2.7V ≤ V_{CC} ≤ 3.6V), I_F = 7.5mA unless otherwise specified. All typicals at T_A = 25°C, V_{CC} = 3.3V.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition	Fig.	Note
Input								
Input Forward Voltage	V_F	—	1.38	1.80	V	I_F=10mA, T_A=25°C	5	
Input Forward Voltage Temperature Coefficient	$\Delta V_F/\Delta T$	—	-1.5	—	mV/°C	I_F=10mA		
Input Reverse Voltage	BV_R	5.0	—	—	V	I_R = 10μA		
Input Threshold Current	I_{TH}	—	2.1	5	mA	V_{CC} = 5.5V, V_O=0.6V $I_{OL} \geq$ 13mA	6	
Input Capacitance	C_{IN}	—	34	—	pF	V_F=0; f=1MH$_Z$		
Detector								
Logic low output voltage	V_{OL}	—	0.09	0.6	V	V_{CC} = 5.5V, I_F = 5mA, I_{OL} (sinking) = 13mA	8	
Logic high output current	I_{OH}	—	1.12	100	μA	V_{CC} = 5.5V, V_O = 5.5V, I_F = 250μA	4	
Logic low supply current	I_{CCL}	—	7.2	10	mA	V_{CC} = 5.5V, I_F = 10mA		1
Logic high supply current	I_{CCH}	—	7.6	10	mA	V_{CC} = 5.5V, I_F = 0mA		1

Specified over recommended temperature (T_A = -40°C to +110°C, 4.5V ≤ V_{CC} ≤ 5.5V), I_F = 7.5mA unless otherwise specified.

All typicals at T_A = 25°C, V_{CC} = 5.0V.

6. SWITCHING SPECIFICATION

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition	Note
Propagation Delay Time to High Output Level	t_{PLH}	20	50	90	ns	R_L = 350Ω, C_L =15pF	3
Propagation Delay Time to Low Output Level	t_{PHL}	25	44	75	ns		4
Pulse Width Distortion	$\|t_{PLH} - t_{PHL}\|$	—	10	—	ns		—
Propagation Delay Skew	t_{PSK}	—	—	40			—
Output Rise Time (10 to 90%)	t_r	—	11	—	ns		—
Output Fall Time (90 to 10%)	t_f	—	2.3	—	ns		—

Specified over recommended temperature (T_A = -40ºC to +110ºC, 2.7V ≤ V_{CC} ≤ 3.6V), I_F = 7.5mA unless otherwise specified.

All typicals at T_A = 25ºC, V_{CC} = 3.3V.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition	Note
Propagation Delay Time to High Output Level	t_{PLH}	25	50	75	ns	TA = 25ºC; R_L=350Ω, C_L =15pF	3
		—	—	100			
Propagation Delay Time to Low Output Level	t_{PHL}	25	40	75	ns	TA = 25ºC; R_L=350Ω, C_L =15pF	4
		—	—	100			
Pulse Width Distortion	$\|t_{PLH} - t_{PHL}\|$	—	10	—	ns	R_L = 350Ω, C_L =15pF	—
Propagation Delay Skew	t_{PSK}	—	—	40			—
Output Rise Time (10 to 90%)	t_r	—	11	—	ns		—
Output Fall Time (90 to 10%)	t_f	—	2.3	—	ns		—

Specified over recommended temperature (T_A = -40ºC to +110ºC, 4.5V ≤ V_{CC} ≤ 5.5V), I_F = 7.5mA unless otherwise specified. All typicals at T_A = 25ºC, V_{CC} = 5.0V.

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition	Note
Logic High Common Mode Transient Immunity	$\|CM_H\|$	10	15	—	kV/μs	V_{CC} = 3.3V V_{CM} = 1000V R_L = 350Ω I_F = 0mA T_A = 25°C	7
		10	15	—		V_{CC} = 5V V_{CM} = 1000V R_L = 350Ω I_F = 0mA T_A = 25°C	
Logic Low Common Mode Transient Immunity	$\|CM_L\|$	10	15	—	kV/μs	V_{CC} = 3.3V V_{CM} = 1000V R_L = 350Ω I_F = 10.0mA T_A = 25°C	8
		10	15	—		V_{CC} = 5V V_{CM} = 1000V R_L = 350Ω I_F = 10.0mA T_A = 25°C	

7. ISOLATION CHARACTERISTIC

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition	Note
Input-Output Insulation Leakage Current	I_{I-O}	—	—	1.0	μA	45% RH, t = 5s, V_{I-O} = 3kV DC, T_A =25ºC	9
Withstand Insulation Test Voltage	V_{ISO}	5000	—	—	V_{RMS}	RH ≤ 50%, t = 1min, T_A = 25ºC	9, 10
Input-Output Resistance	R_{I-O}	—	10^{12}	—	Ω	V_{I-O} = 500V DC	9,
Input-Output Capacitance	C_{I-O}	—	1.0	—	p	f = 1MHz, T_A = 25ºC	9,

Specified over recommended temperature (T_A = -40ºC to +110ºC) unless otherwise specified.Typical values applies to T_A = 25ºC

Notes

1. A 0.1μF or bigger bypass capacitor for V_{CC} is needed as shown in Fig.1
2. Peaking driving circuit may be used to speed up the LED. The peak drive current of LED may go up to 50mA and maximum pulse width 50ns, as long as average current doesn't exceed 20mA.
3. t_{PLH} (propagation delay) is measured from the 3.75 mA point on the falling edge of the input pulse to the 1.5 V point on the rising edge of the output pulse.
4. t_{PHL} (propagation delay) is measured from the 3.75 mA point on the rising edge of the input pulse to the 1.5 V point on the falling edge of the output pulse.
5. CM_H is the maximum tolerable rate of rise of the common mode voltage to assure that the output will remain in a high logic state (i.e., VO > 2.0 V).
6. CM_L is the maximum tolerable rate of fall of the common mode voltage to assure that the output will remain in a low logic state (i.e., VO < 0.8 V).
7. Device is considered a two-terminal device: pins 1, 2, 3 and 4 shorted together, and pins 5, 6, 7 and 8 shorted together.
8. In accordance with UL1577, each optocoupler is proof tested by applying an insulation test voltage 5250Vrms for one second (leakage current less than 10 μA). This test is performed before the 100% production test for partial discharge

8. TEST CIRCUITS

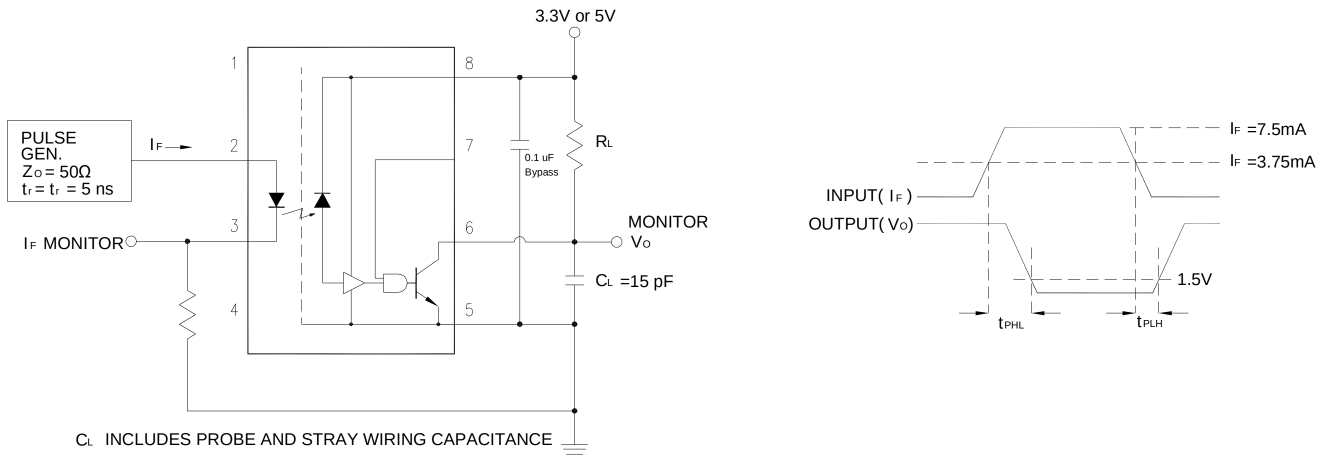


Figure 1: Test Circuit for t_{PHL} and t_{PLH}

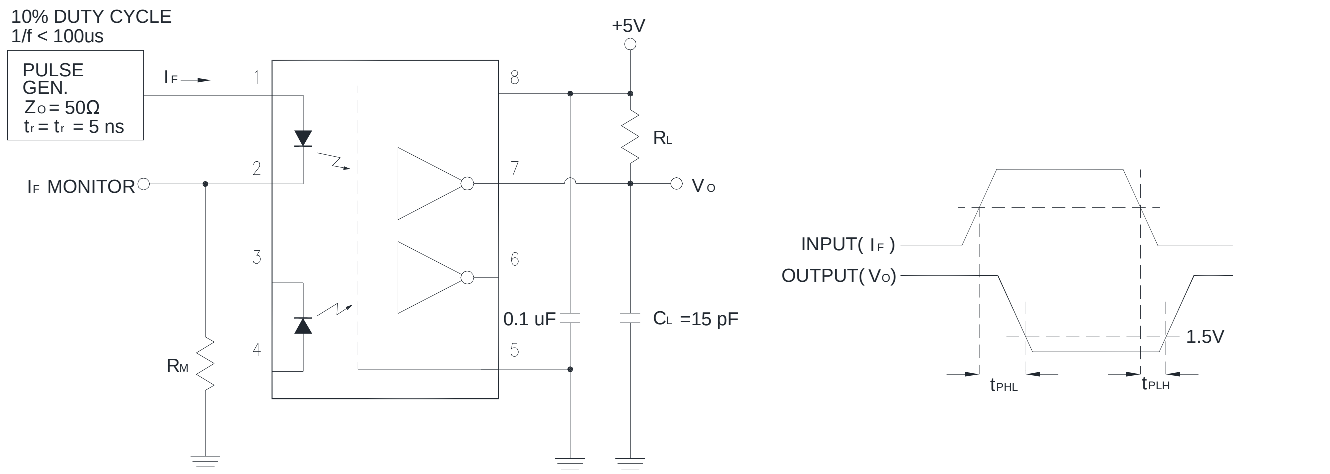


Figure 2: Single Channel Test Circuit for Common Mode Transient Immunity

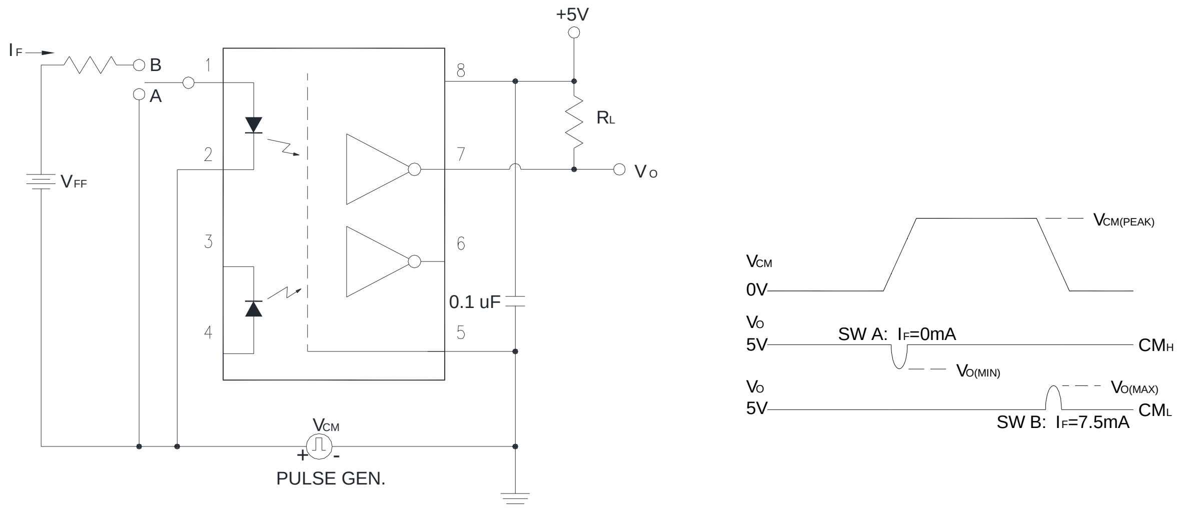


Figure 3: Single Channel Test Circuit for Common Mode Transient Immunity

9. CHARACTERISTIC CURVES

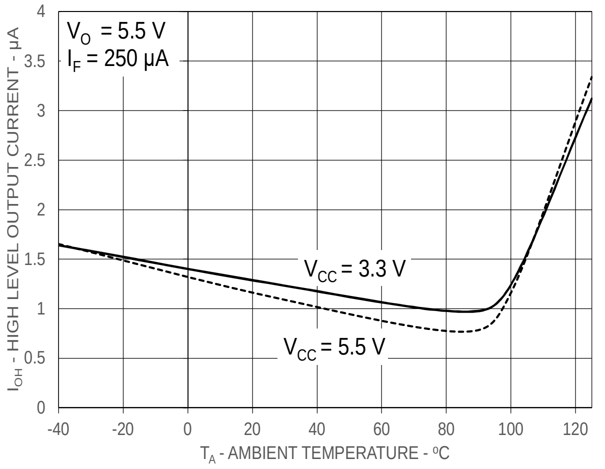


Figure 4: Typical High Level Output Current vs. Ambient Temperature

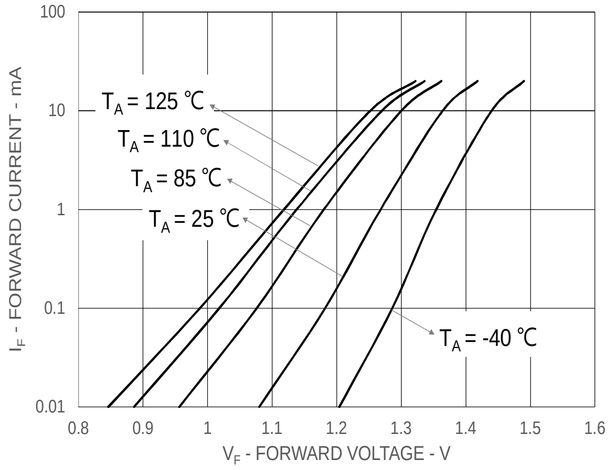


Figure 5: Typical Input Diode Forward Characteristic

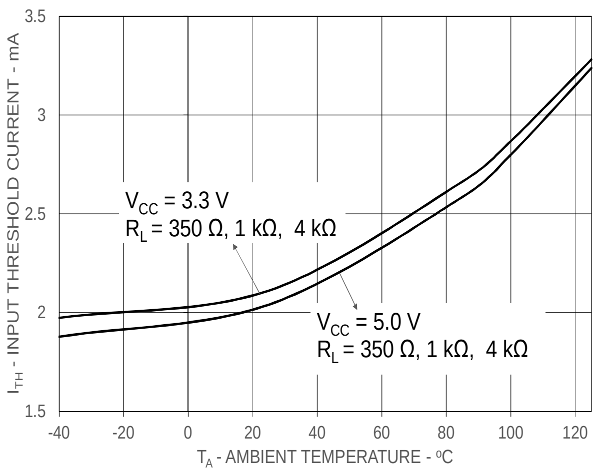


Figure 6: Typical Input Diode Threshold Current vs. Ambient Temperature

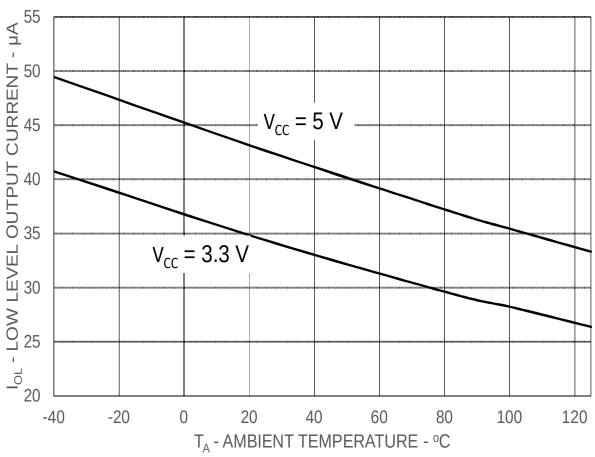


Figure 7: Typical Low Level Output Current vs. Ambient Temperature

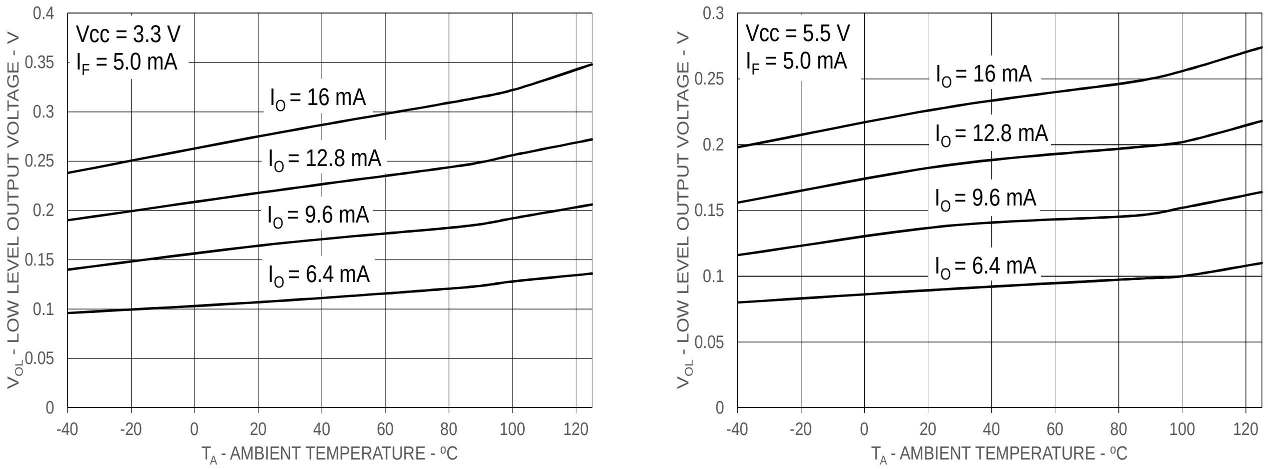


Figure 8: Typical Low Level Output Voltage vs. Ambient Temperature

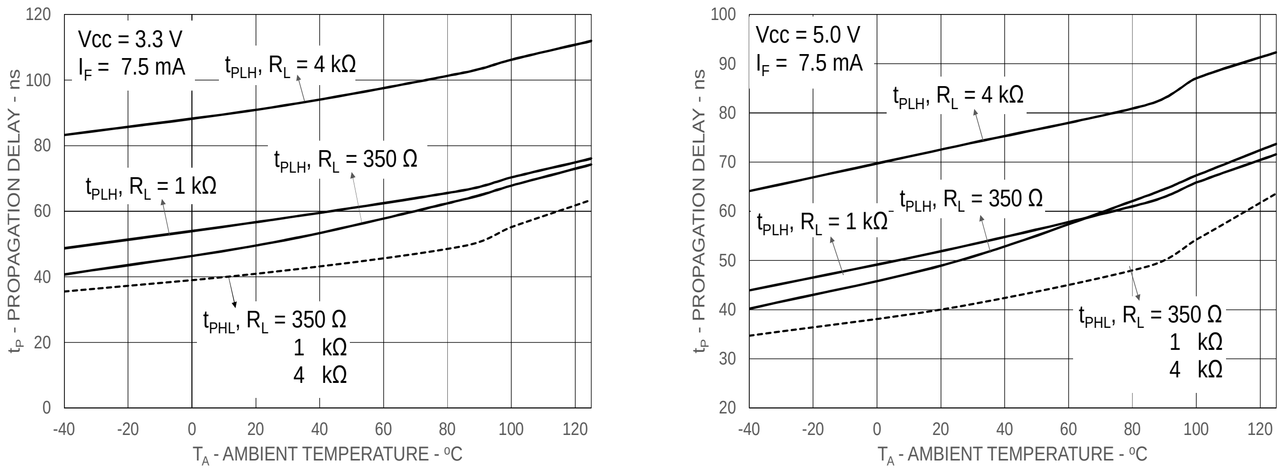


Figure 9: Typical Propagation Delay vs. Ambient Temperature

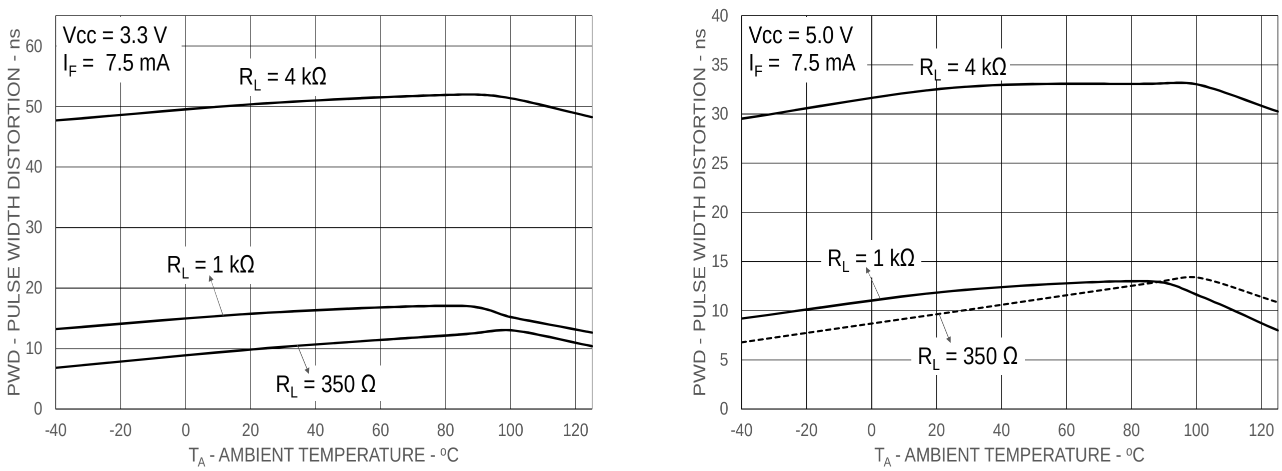


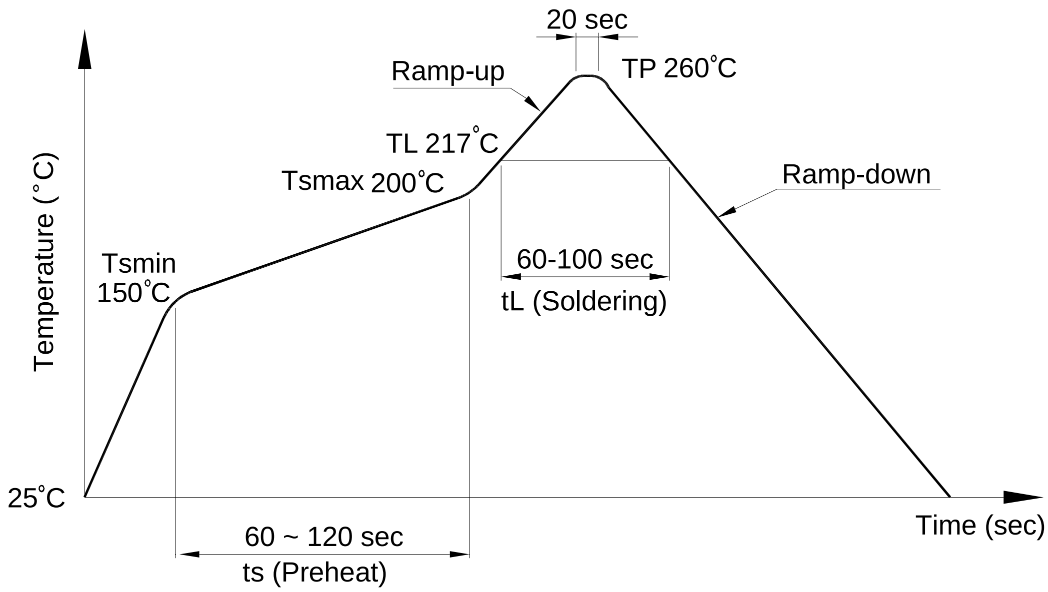
Figure 10: Typical Pulse Width Distortion vs. Ambient Temperature

10. TEMPERATURE PROFILE OF SOLDERING

10.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions
Preheat	
- Temperature Min (T_{Smin})	150˚C
- Temperature Max (T_{Smax})	200˚C
- Time (min to max) (ts)	90±30 sec
Soldering zone	
- Temperature (T_L)	217˚C
- Time (t_L)	60 ~ 100 sec
Peak Temperature (T_P)	260˚C
Ramp-up rate	3˚C / sec max.
Ramp-down rate	3~6˚C / sec



10.2 Wave soldering (JEDEC22A111 compliant)

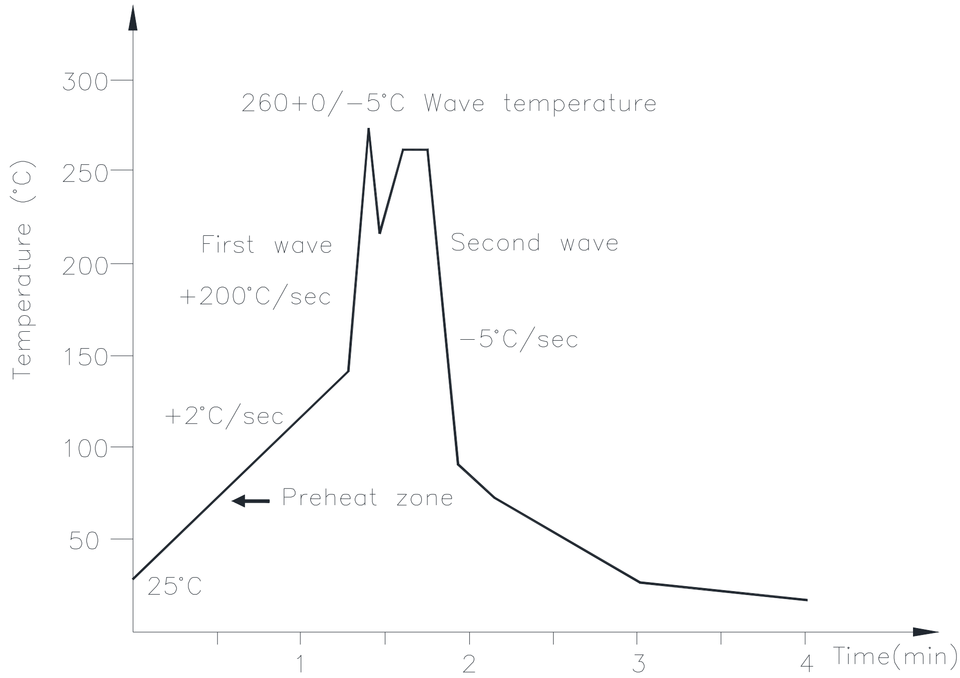
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5˚C

Time: 10 sec.

Preheat temperature:25 to 140˚C

Preheat time: 30 to 80 sec.



10.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5˚C

Time: 3 sec max.

11. NOTES

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any “specific” application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit’s body in solder paste is not recommended.